

Vishay Siliconix

N-Channel 20-V (D-S) MOSFETs

PRODUCT SUMMARY			
V _{DS} (V)	$r_{DS(on)}$ (Ω)	I _D (A)	
20	0.4 at $V_{GS} = 4.5 \text{ V}$	0.73	
20	$0.5 \text{ at V}_{GS} = 2.5 \text{ V}$	0.65	

FEATURES

• TrenchFET® Power MOSFET

ESD Protected: 4000 V



ROHS

APPLICATIONS

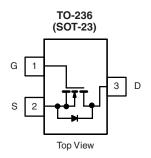
• Direct Logic-Level Interface: TTL/CMOS

• Drivers: Relays, Solenoids, Lamps, Hammers

• Battery Operated Systems, DC/DC Converters

Solid-State Relays

• Load/Power Switching-Cell Phones, Pagers

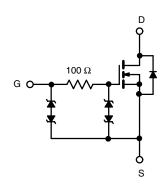


Marking Code: K2ywl

K2 = Part Number Code for TN0200K

y = Year Code w = Week Code I = Lot Traceability

Ordering Information: TN0200K-T1-E3 (Lead (Pb)-free)



ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	20	V	
Gate-Source Voltage		V _{GS}	± 8		
Continuous Drain Current (T _{.I} = 150 °C) ^b	T _A = 25 °C	I_	0.73		
Continuous Drain Current (1 _J = 150 °C) ³	T _A = 70 °C	- I _D	0.58	٨	
Pulsed Drain Current ^a		I _{DM}	4	A	
Continuous Source Current (Diode Conduction) ^b		I _S	0.3		
Bound Biodination b	T _A = 25 °C	P _D	0.35	W	
Power Dissipation ^b	T _A = 70 °C	' D	0.22	VV	
Operating Junction and Storage Temperature Range		T _{J,} T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS				
Parameter	Symbol	Limit	Unit	
Maximum Junction-to-Ambient ^b	R _{thJA}	357	°C/W	

Notes

- a. Pulse width limited by maximum junction temperature.
- b. Surface Mounted on FR4 Board, $t \le 10$ sec.

TN0200K

Vishay Siliconix



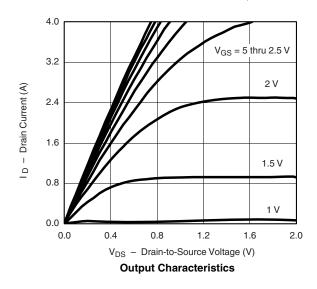
SPECIFICATIONS T _A = 25 °C, unless otherwise noted							
			Limits				
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 10 \mu\text{A}$	20			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 50 \mu A$	0.45	0.6	1.0		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 5		
Zero Gate Voltage Drain Current	la a a	V _{DS} = 20 V, V _{GS} = 0 V			0.1	μΑ	
	I _{DSS}	T _J = 55 °C			10		
On-State Drain Current ^a	1	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2.5			А	
	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 2.5 \text{ V}$	1.5				
Drain-Source On-Resistance ^a	F	$V_{GS} = 4.5 \text{ V}, I_D = 0.6 \text{ A}$		0.2	0.4	Ω	
	r _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 0.6 \text{ A}$		0.25	0.5		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 5 \text{ V}, I_{D} = 0.6 \text{ A}$		2.2		S	
Diode Forward Voltage ^a	V _{SD}	I _S = 0.3 A, V _{GS} = 0 V		0.8	1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_D = 0.6 \text{ A}$		1400	2000		
Gate-Source Charge	Q _{gs}			190		pC	
Gate-Drain Charge	Q_{gd}			300			
Gate Resistance	R _g			105		Ω	
Turn-On Delay Time	t _{d(on)}	V_{DD} = 10 V, R_L = 16 Ω $I_D \cong 0.6$ A, V_{GEN} = 4.5 V R_g = 6 Ω		17	25	- ns	
Rise Time	t _r			20	30		
Turn-Off Delay Time	t _{d(off)}			55	85		
Fall Time	t _f			30	45		

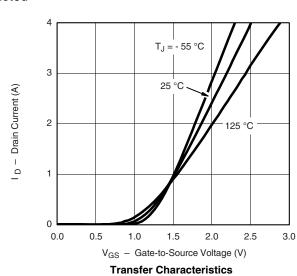
Notes:

- a. Pulse test: PW \leq 300 μs duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

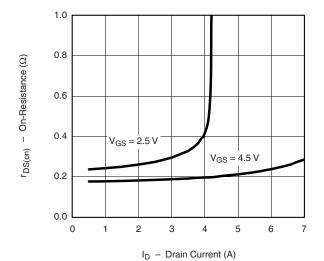




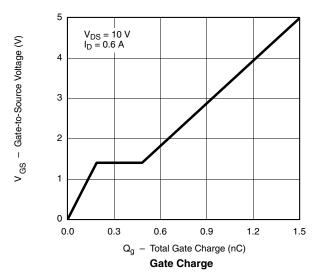


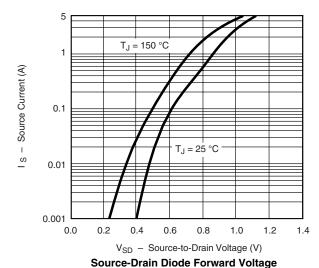
Vishay Siliconix

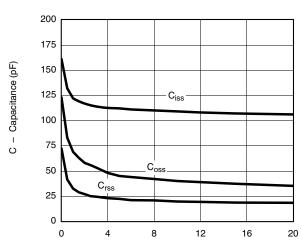
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



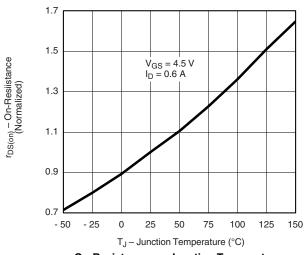
On-Resistance vs. Drain Current



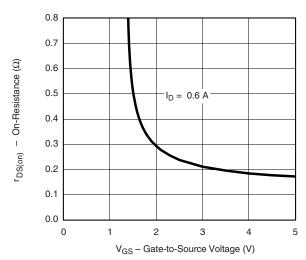




V_{DS} - Drain-to-Source Voltage (V) **Capacitance**



On-Resistance vs. Junction Temperature

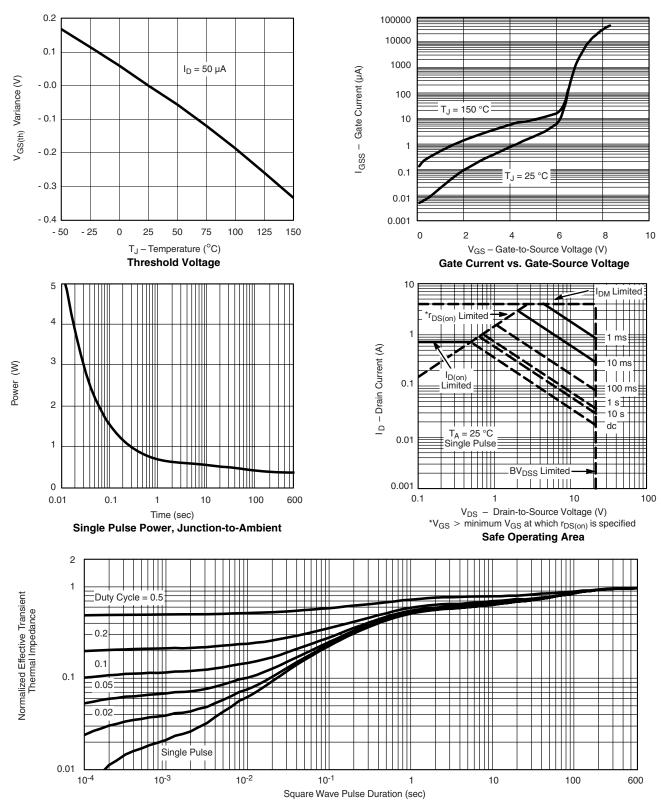


On-Resistance vs. Gate-Source Voltage

Vishay Siliconix

VISHAY.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Effective Transient Thermal Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?72678.



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.

Document Number: 91000 Revision: 18-Jul-08